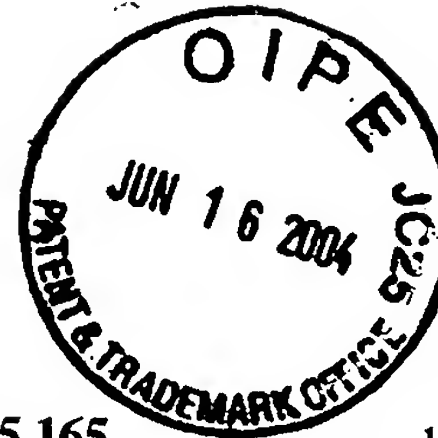


COPY



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Applicant(s): **Joseph Young J. PAIK** Application No.: **10/665,165** 107262.179 US2
Filing Date: **September 18, 2003** Atty Docket No.: **007734 FPS/MMCS/APC** SMA/lrm
Entitled: **Feedback Control of a Chemical Mechanical Polishing Process for Multi-Layered Films**

RECEIPT IS ACKNOWLEDGED FOR THE FOLLOWING:

- [X] Information Disclosure Statement
- [X] 26 Pages of Form PTO-1449
- [X] 267 References

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Joseph Young J. PAIK

Serial No. 10/665,165

Filed: September 18, 2003

.....

Group Art Unit:

Examiner:

For: FEEDBACK CONTROL OF A CHEMICAL MECHANICAL POLISHING PROCESS FOR MULTI-LAYERED FILMS

INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

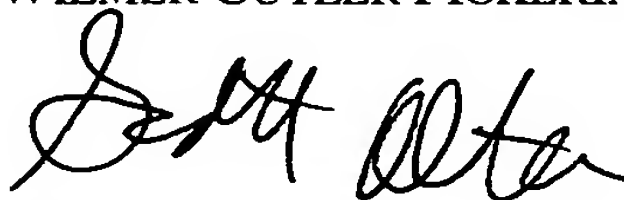
publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

The references listed on Sheet 1 of the attached PTO-1449 Forms were cited in a patentability investigation and/or a corresponding foreign or PCT application relating to the above-referenced application. The remaining references are from potentially related patent applications, and possibly other sources.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

WILMER CUTLER PICKERING HALE AND DORR LLP



Scott M. Alter
Registration No. 32,879

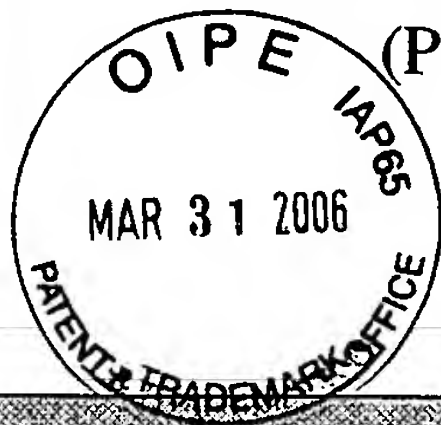
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Date: 6/16/04

**INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION**
(PTO-1449)



ATTY. DOCKET NO.
007734 FPS/MMCS/APC

SERIAL NO.
10/665,165

APPLICANT
Joseph Young J. PAIK

FILING DATE
September 18, 2003

GROUP

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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
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EXAMINER

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U.S. PATENT DOCUMENTS							
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U.S. PATENT DOCUMENTS							
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U.S. PATENT DOCUMENTS							
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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				APPLICANT Joseph Young J. PAIK			
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	09/469,227	12/22/99	Somekh et al.	Multi-Tool Control System, Method and Medium			
	09/619,044	07/19/00	Yuan	System and Method of Exporting or Importing Object Data in a Manufacturing Execution System			
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	09/655,542	09/06/00	Yuan	System, Method and Medium for Defining Palettes to Transform an Application Program Interface for a Service			
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	10/100,184	03/19/02	Al-Bayati et al.	Method, System and Medium for Controlling Semiconductor Wafer Processes Using Critical Dimension Measurements			
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
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	01-283934	11/15/89	Japan			X	
	0 397 924 A1	11/22/90	Europe			X	
	2,050,247	08/29/91	Canada			X	
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	05-151231	06/18/93	Japan			X	
	05-216896	08/27/93	Japan			X	
	05-266029	10/15/93	Japan			X	
	06-110894	04/22/94	Japan			X	
	06-176994	06/24/94	Japan			X	
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	EP 0 621 522 A2	10/26/94	Europe			X	
	WO 95/34866	12/21/95	WO			X	
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	10-34522	02/10/98	Japan			X	
	10-173029	06/26/98	Japan			X	
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						Yes	No
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	WO 98/45090	10/15/98	WO			X	
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	EP 0 910 123 A1	04/21/99	Europe			X	
	11-126816	05/11/99	Japan			X	
	11-135601	05/21/99	Japan			X	
	WO 99/25520	05/27/99	WO			X	
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	WO 99/59200	11/18/99	WO			X	
	WO 00/00874	01/06/00	WO			X	
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						Yes	No
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	WO 01/25865 A1	04/12/01	WO			X	
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<p>EXAMINER</p>	<p>DATE CONSIDERED</p>	

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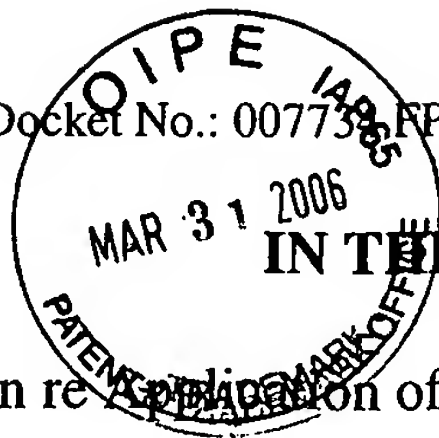
Applicant(s): **Joseph Young J. PAIK** Application No.: **10/665,165** 107262.179 US2
Filing Date: **September 18, 2003** Atty Docket No.: **007734 FPS/MMCS/APC** SMA/lrm
Entitled: **Feedback Control of a Chemical Mechanical Polishing Process for Multi-Layered Films**

RECEIPT IS ACKNOWLEDGED FOR THE FOLLOWING:

- [X] Supplemental Information Disclosure Statement and 4 PTO-1449 Forms
- [X] 26 References

Docket No.: 007738 FPS/MMCS/APC

PATENT/OFFICIAL



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Joseph Young J. PAIK

Serial No. 10/665,165

Filed: September 18, 2003

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: Group Art Unit:
:
: Examiner:

For: FEEDBACK CONTROL OF A CHEMICAL MECHANICAL POLISHING PROCESS
FOR MULTI-LAYERED FILMS

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom. Copies of any cited U.S. Patents and U.S. Patent Publications are not being submitted in accordance with 37 CFR 1.98(a)(2)(i).

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

In accordance with 37 C.F.R. § 1.97(g) and (h), the filing of this IDS should not be construed as a representation that a search had been made or that information cited is, or is considered to be, material to patentability as defined in 37 C.F.R. § 1.56 (b), or that any cited document listed or attached is (or constitutes) prior art. Unless otherwise indicated, the date of

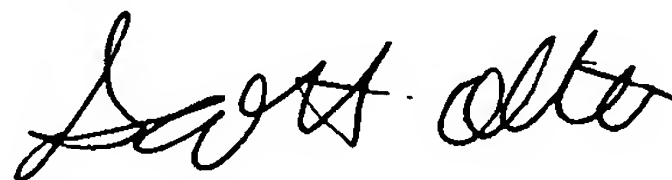
Serial No. 10/665,165

publication indicated for an item is taken from the face of the item, and Applicant reserves the right to prove that the date of publication is in fact different.

No fee is believed to be required; however, the Commissioner is authorized to charge any deficiency in any fees pursuant to 37 CFR § 1.17 associated with this communication and to credit any excess payment to Deposit Account No. 08-0219.

Respectfully submitted,

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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449)				ATTY. DOCKET NO. 007734 FPS/MMCS/APC		SERIAL NO. 10/665,165	
				APPLICANT Joseph Young J. PAIK			
				FILING DATE September 18, 2003		GROUP	
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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
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